# *CDP1857C*

March 1997

# 4-Bit Bus Buffer/Separator

#### **Features**

- Provides Easy Connection of I/O to CDP1800-Series Microprocessor Data Bus
- Non-Inverting Fully Buffered Data Transfer

### Ordering Information

PART NUMBER	TEMP. RANGE	PACKAGE	PKG. NO.
CDP1857CE	-40°C to +85°C	PDIP	E16.3
CDP1857CD	-40°C to +85°C	SBDIP	D16.3

TABLE 1. CDP1857 FUNCTION FOR I/O BUS SEPARATOR **OPERATION** 

cs	MRD	DATA BUS OUT DB0-DB3	DATA OUT DO0-DO3
0	Х	High Impedance	High Impedance
1	0	High Impedance	Data Bus
1	1	Data In	High Impedance

### Description

The CDP1857C is a 4-bit CMOS non-inverting bus separator designed for use in CDP1800-series microprocessor systems. It can be controlled directly by a 1800-series microprocessor without the use of additional components.

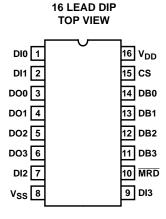
The CDP1857 is designed for use as a bus buffer or separator between the 1800-series microprocessor data bus and I/O devices. It provides a chip-select (CS) input signal which, when high (1), enables the bus-separator three-state output drivers. The direction of data flow, when enabled, is controlled by the  $\overline{MRD}$  input signal.

In the CDP1857, when  $\overline{\text{MRD}} = 1$ , it enables the three-state bus drivers (DB0-DB3) and transfers data from the DATA-IN lines onto the data bus. When  $\overline{MRD} = 0$ , it disables the three-state bus drivers (DB0-DB3) and enables the three-state data output drivers (DO0-DO3), thus, transferring data from the data bus to the DATA-OUT terminals.

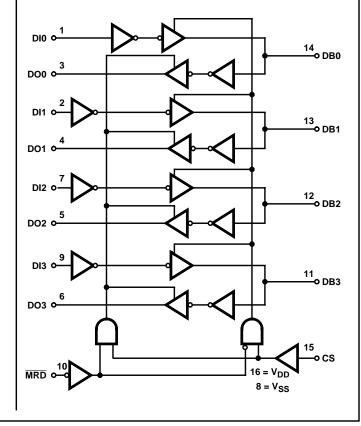
The CDP1857 can be used as a bidirectional bus buffer by connecting the corresponding DI and DO terminals (Figure 1). The MRD output signal from the 1800-series microprocessor has the correct polarity to control the CDP1857 when it is used as I/O bus buffer/separator. Therefore, the 1800-series microprocessor MRD signal can be connected directly to the MRD input of CDP1857. See Function Table 1 for use of the CDP1857 as an I/O bus buffer/separator.

The CDP1857C is supplied in 16-lead hermetic, dual-in-line ceramic packages (D suffix), and in 16-lead plastic packages (E suffix).

#### Pinout



# Functional Diagram For CDP1857



#### **CDP1857C**

#### **Absolute Maximum Ratings**

DC Supply Voltage Range, ( $V_{DD}$ ) (All Voltages Referenced to  $V_{SS}$  Terminal).....-0.5V to +7V Input Voltage Range, All Inputs .....-0.5V to  $V_{DD}$  +0.5V DC Input Current, Any One Input.....±10mA

#### **Thermal Information**

Thermal Resistance (Typical)	θ <sub>JA</sub> (ºC/W)	θ <sub>JC</sub> (°C/W)
PDIP Package	85	N/A
SBDIP Package	85	22
Device Dissipation Per Output Transistor		
T <sub>A</sub> = Full Package Temperature Range		
(All Package Types)		100mW
Operating Temperature Range (T <sub>A</sub> )		
Package Type D	55 <sup>c</sup>	C to +125°C
Package Type E	40	OC to +85°C
Storage Temperature Range (TSTG)	65 <sup>0</sup>	°C to +150°C
Lead Temperature (During Soldering)		+265°C
At distance $1/16 \pm 1/32$ In. $(1.59 \pm 0.79)$	mm)	
from case for 10s max		

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

# Static Electrical Specifications At $T_A = -40^{\circ}\text{C}$ to +85°C, Except as Noted:

		CONDITIONS						
PARAMETER	SYMBOL	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	MIN	(NOTE 1) TYP	MAX	UNITS
Quiescent Device Current	I <sub>DD</sub>	-	0, 5	5	-	5	50	μΑ
Output Low Drive (Sink) Current	I <sub>OL</sub>	0.4	0, 5	5	1.6	3.2	-	mA
Output High Drive (Source) Current	loh	4.6	0, 5	5	-1.15	-2.3	-	mA
Output Voltage Low-Level (Note 3)	V <sub>OL</sub>	-	0, 5	5	-	0	0.1	V
Output Voltage High-Level (Note 3)	V <sub>OH</sub>	-	0, 5	5	4.9	5	-	V
Input Low Voltage	V <sub>IL</sub>	0.5, 4.5	-	5	-	-	1.5	V
Input High Voltage	V <sub>IH</sub>	0.5, 4.5	-	5	3.5	-	-	V
Input Leakage Current	I <sub>IN</sub>	Any Input	0, 5	5	-	-	1	μΑ
Operating Current (Note 2)	I <sub>DD1</sub>	0, 5	0, 5	5	-	50	100	μΑ
Input Capacitance	C <sub>IN</sub>	-	-	-	-	5	7.5	pF

#### NOTES:

- 1. Typical values are for  $T_A = +25^{\circ}C$  and nominal voltage.
- 2. Operating current measured in a CDP1802 system at 3.2MHz with outputs floating.
- 3.  $I_{OL} = I_{OH} = 1\mu A$ .

# $\textbf{Dynamic Electrical Specifications} \quad \text{At T}_{A} = -40^{o}\text{C to } +85^{o}\text{C}, \ V_{DD} = 5\text{V} \pm 5\%, \ V_{IH} = 0.7 \ V_{DD}, \ V_{IL} = 0.3 \ V_{DD}, \ t_{R}, \ t_{F} = 20\text{ns}, \ C_{L} = 100\text{pF}$

PARAMETER	SYMBOL	V <sub>DD</sub> (V)	(NOTE 1) TYP	MAX	UNITS
Propagation Delay Time:					
MRD or CS to DO	t <sub>ED</sub>	5	150	225	ns
MRD or CS to DB	t <sub>EB</sub>	5	150	225	ns
DI to DB	t <sub>IB</sub>	5	100	150	ns
DB to DO	t <sub>BO</sub>	5	100	150	ns

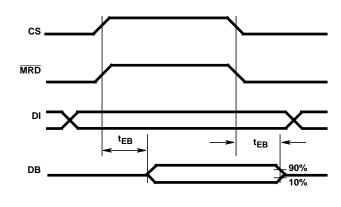
#### NOTE:

1. Typical values are for  $T_A = 25^{\circ}C$  and nominal voltages.

 $\label{eq:Recommended Operating Conditions} \textbf{At T}_{A} = \textbf{Full Package Temperature Range.For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:}$ 

PARAMETER	MIN	MAX	UNITS	
Supply-Voltage Range	4	6.5	V	
Recommended Input Voltage Range	V <sub>SS</sub>	V <sub>DD</sub>	V	

# **Timing Diagrams**



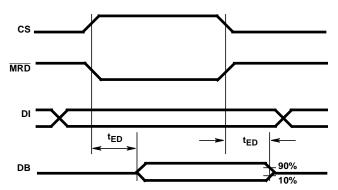
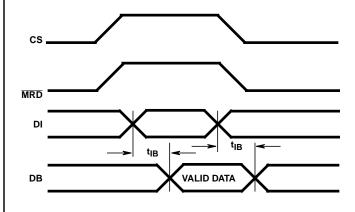


FIGURE 1A. ENABLE TO DB TIME

FIGURE 1B. ENABLE TO DO TIME



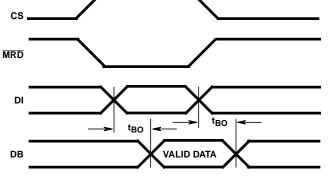


FIGURE 1C. DI TO DB TIME

FIGURE 1D. DB TO DO TIME

FIGURE 1. TIMING DIAGRAMS FOR CDP1857C

# **Typical Applications**

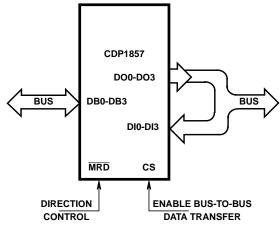


FIGURE 2. CDP1857 BIDIRECTIONAL BUS BUFFER OPERATION

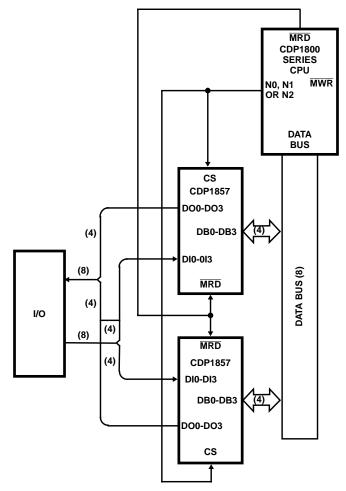


FIGURE 3. CDP1857 BUS SEPARATOR OPERATION

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